



Contribution ID: 340

Type: **Poster**

## **Effect of Shelf Life to Void Under Die for Die Attach Process in Integrated Packaging**

*Thursday, 25 May 2017 17:45 (15 minutes)*

This research studied about reduction of void under die in die attach process. Die attach process is one that is very importance process in the integrated circuit(IC) packaging. A popular adhesive material used for attaching between die and leadframe or substrate of a package which is an epoxy. Snap cure process is also important to make a completed epoxy due to cross linking to enhance microstructure of epoxy stiffness. The shelf life before snap cure process effect to void under die of multichip package because of a long time of attaching cause risk to happen void under die. In experiment, the wait time before snap cure were varied from 0 until 8 hours with a step of 1 hour and analyzed the void under die of epoxy by die shear test, x-ray and reliability test after take the test samples out from the snap cure. The results confirmed that the wait time effect to void under die of die attach process in IC packaging.

**Primary author:** PAKTRAMOOK, varunee

**Co-authors:** Mr SUMITHPIBUL, Chalerm Sak (King Mongkut's University of Technology North Bangkok, Bangkok,10800); Dr UGSORNRAT, Kessarat; Mr DISPONG, Nuttakull (Department of Engineering, NXP Manufacturing(Thailand) LTD, Bangkok,21210)

**Presenter:** PAKTRAMOOK, varunee

**Session Classification:** Poster Presentation II

**Track Classification:** Magnetic and Semiconductor Physics